shows package 200 that includes four dies 202, 204, 206, 208 that are connected by a interconnect hub 218. In embodiments, the interconnect hub 218 overlaps a corner of each of the dies 202, 204, 206, 208 and physically and/or electrically couples with electronics of at least a subset of each of the dies.

[0032] This interconnect hub 218 may include a passive or an active silicon bridge that intersects a corner, respectively, of the four tiled surface mount dies 202, 204, 206, 208.

[0033] The die-to-die communication flow 250 shows possible communication paths that may be facilitated by the interconnect hub 218. In embodiments, each of the individual flows may be implemented by high-bandwidth, high-speed data connection that may exist in one or more layers within the interconnect hub 218. For example, using the interconnect hub 218 die 1 202 may communicate directly with die 2 204, die 3 206, and/or die 4 208.

[0034] In embodiments, each of the dies 202, 204, 206, 208 may be different types of dies, including dies from different manufacturers, that are communicatively coupled by the interconnect hub 218. In embodiments, the dies may be a same die that may have communications circuitry designed in a particular corner area of the die. When the dies 202, 204, 206, 208 are tiled, they may be positioned in a clockwise layout, where each die is rotated 90° such that the particular corner area having the communications circuitry is proximate to the other dies and may be electrically coupled with interconnect hub 218.

[0035] **FIGs. 3A-3C** illustrates examples of attaching an interconnect hub to a plurality of dies, in accordance with embodiments. Attachment embodiments may be configured in a different connectivity solutions. **FIGs. 3A-3B** show an example of configurations that position the interconnect hub mounted on top of the tiled dies. This allows for a direct tiled die to package connection for more direct power delivery and high speed IO routing. There are two variants